

C0603X241GATACTU

Aliases (C0603X241GATAC7867)

Specifications

Insulation Resistance

SMD Comm X8G HT150C Flex, Ceramic, 240 pF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Capacitance	240 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	250 VDC
Dielectric Withstanding V	oltage 625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and C Applied (TCC)	
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee

Time is 1000 Hours

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

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